

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
GAKU FURUTA	12/01/2010
SOO YOUNG CHOI	12/01/2010
OMORI KENJI	12/20/2010
RECEIVING PARTY DATA	
Name:	APPLIED MATERIALS, INC.
Street Address:	P.O. BOX 450A
Internal Address:	LEGAL AFFAIRS DEPT.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95052
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12913846
CORRESPONDENCE DATA	
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
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ATTORNEY DOCKET NUMBER:	AM14721/DISPLAY/DP
NAME OF SUBMITTER:	ROBERT W MUCLCAHY
Total Attachments: 4	

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**PATENT
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source=14721 US ASG 2010-12-21#page4.tif

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Gaku Furuta 1080 Firth Court Sunnyvale, California 94087	2)	Soo Young Choi 40907 Rioja Court Fremont, California 94539
3)	Omori Kenji 15-11 Narita Higashi Machi Neyagawa-City, Osaka 575-0001 JAPAN		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

THIN FILM TRANSISTORS HAVING MULTIPLE DOPED SILICON LAYERS

for which application for Letters Patent in the United States was filed on October 28, 2010, under Serial No. 12/913,846, executed on even date herewith; and

WHEREAS, APPLIED MATERIALS, INC., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

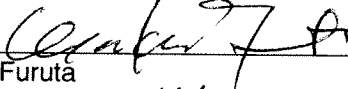
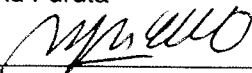
2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition

proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>12/1/10</u> (DATE)	 _____ Gaku Furuta
2)	<u>12/1/10</u> (DATE)	 _____ Soo Young Choi
3)	_____ (DATE)	_____ Omori Kenji

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1) _____ (DATE)

Gaku Furuta

2) _____ (DATE)

Soo Young Choi

3) 12/20/2010 (DATE)

Omori Kenji

Kenji Omori